

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2768911

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PAN SOO KIM	03/10/2014
DUK HAENG LEE	03/10/2014
WOON SUK JUNG	03/10/2014
RECEIVING PARTY DATA	
Name:	HOJIN PLATECH CO., LTD.
Street Address:	15 BLOCK 1 LOT, BANWOL INDUSTRIAL COMPLEX
Internal Address:	MONKNAE-RO 119-91, DANWON-GU, GYEONGGI-DO
City:	ANSAN-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	425-100
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14174754
CORRESPONDENCE DATA	
Fax Number:	(858)720-5799
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	8587205700
Email:	mbright@perkinscoie.com
Correspondent Name:	BING AI
Address Line 1:	PERKINS COIE LLP
Address Line 2:	PO BOX 1247
Address Line 4:	SEATTLE, WASHINGTON 98111-1247
ATTORNEY DOCKET NUMBER:	112174-8003.US00
NAME OF SUBMITTER:	BING AI
SIGNATURE:	/Bing Ai/
DATE SIGNED:	03/14/2014
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 12	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Pan Soo Kim et al.

Application No.: 14/174,754

Confirmation No.: 1088

Filed: February 6, 2014

For: COPPER PLATING SOLUTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA22313-1450

DECLARATION AND ASSIGNMENT BY THE INVENTOR
UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012

I, Pan Soo Kim, hereby declare that:

I believe I am an original joint inventor of a claimed invention in a patent application entitled:

COPPER PLATING SOLUTION

the specification of which was filed at the U.S. Patent and Trademark Office on February 6, 2014, as Application Serial No. 14/174,754, and identified as Attorney Docket No. 112174-8003.US00.

I believe the following persons are additional original joint inventors of the above-identified patent application:

DukHaeng Lee of Bucheon-Si, Republic of Korea; and
Woon Suk Jung of Ansan-Si, Republic of Korea.

I made, authorized to make, or will make or authorize to make the above-identified patent application at the U.S. Patent and Trademark Office.

Inventor : Kim et al.
Appl. No. : 14/174,754
Filed : February 6, 2014
Page : 2 of 4

Docket No.:112174-8003.US00

I have reviewed and understand the contents of the above-identified patent application including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

I hereby assign to HojinPlatech Co., Ltd., a corporation of Republic of Korea, having a place of business at 15 Block 1Lot, Banwol Industrial Complex, Monknae-ro 119-91, Danwon-Gu, Ansan-Si, Gyeonggi-do, 425-100, Republic of Korea, and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in an application for United States Patent filed by me, entitled *COPPER PLATING SOLUTION*, filed on February 6, 2014, and assigned U.S. Application Number 14/174,754.

This assignment includes the entire right, title and interest in said application, all legal equivalents thereof in any country, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions and improvements, including, but not limited to, all divisions, continuations, reissues, reexamination certificates, any and all certificates issued in any post-grant proceeding, and extensions of said applications and patents of the United States, foreign patents, utility models, and design registrations, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes, and the right to seek relief and recover all damages, including, but not limited to, a reasonable royalty, by reason of infringement or any other violation of patent or patent application rights. I authorize the Assignee to apply in all countries in my name or in the name of the Assignee for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements.

112174-8003.US00/LEGAL29687273.1

In addition, I hereby confirm the sale, assignment, and transfer to the Assignee of the entire right, title and interest throughout the world in said inventions and improvements that occurred by operation of an employment agreement between me and the Assignee existing at the time said inventions and improvements were made. Should I have any remaining interest, I hereby sell, assign, and transfer any right, title and interest I may have in said inventions and improvements anywhere in the world to the Assignee.

The foregoing assignments, sale and transfer have been made for good and valuable consideration in accordance with the aforementioned employment agreement.

I hereby represent and covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with the assignment of said inventions and improvements to the Assignee.

I further covenant for myself and my respective heirs, legal representatives and assigns, to assist the Assignee in handling various procedures, tasks and documentation in connection with this assignment, including, but not limited to, providing to the Assignee promptly upon the request of the Assignee all pertinent facts and documents relating to said invention and improvements, and said patents, said legal equivalents or other legal instrument as may be known and accessible to me and testifying as to the same in any interference, litigation, or proceeding relating thereto, and promptly executing and delivering to the Assignee or its legal representative any and all papers, documents, instruments or affidavits in connection with obtaining, maintaining, issuing or enforcing said application, said inventions and improvements, and said patents, said equivalents and other legal instrument which may be necessary or desirable to carry out the purposes thereof.


I hereby authorize and request the Commissioner of Patents and Trademarks to issue one or more patents in the United States for said inventions and improvements to HojinPlatech Co., Ltd. as assignee of the entire interest, for the sole use and benefit of Assignee, its successors and assigns.

I am competent to execute the above declaration and assignment. I hereby have duly executed the declaration and assignment below with my name.

Inventor : Kim et al.
Appl. No. : 14/174,754
Filed : February 6, 2014
Page : 4 of 4

Docket No.: 112174-8003.US00

Full name of inventor: Pan Soo Kim

Inventor's signature: _____

Date: March 10, 2014

Perkins Coie LLP
P.O. Box 1247
Seattle, Washington 98111-1247
Telephone: (858) 720-5700
Facsimile: (206) 359-7198

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In re Patent Application of:
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DECLARATION AND ASSIGNMENT BY THE INVENTOR
UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012

I, Duk Haeng Lee, hereby declare that:

I believe I am an original joint inventor of a claimed invention in a patent application entitled:

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the specification of which was filed at the U.S. Patent and Trademark Office on February 6, 2014, as Application Serial No. 14/174,754, and identified as Attorney Docket No. 112174-8003.US00.

I believe the following persons are additional original joint inventors of the above-identified patent application:

Pan Soo Kim of Yongin-Si, Republic of Korea; and

Woon Suk Jung of Ansan-Si, Republic of Korea.

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Inventor : Kim et al.
Appl. No. : 14/174,754
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Docket No.: 112174-8003.US00

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I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

I hereby assign to Hojin Plotech Co., Ltd., a corporation of Republic of Korea, having a place of business at 15 Block 1 Lot, Banwol Industrial Complex, Monknae-ro 119-91, Danwon-Gu, Ansan-Si, Gyeonggi-do, 425-100, Republic of Korea, and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in an application for United States Patent filed by me, entitled *COPPER PLATING SOLUTION*, filed on February 6, 2014, and assigned U.S. Application Number 14/174,754.

This assignment includes the entire right, title and interest in said application, all legal equivalents thereof in any country, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions and improvements, including, but not limited to, all divisions, continuations, reissues, reexamination certificates, any and all certificates issued in any post-grant proceeding, and extensions of said applications and patents of the United States, foreign patents, utility models, and design registrations, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes, and the right to seek relief and recover all damages, including, but not limited to, a reasonable royalty, by reason of infringement or any other violation of patent or patent application rights. I authorize the Assignee to apply in all countries in my name or in the name of the Assignee for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements.

Inventor : Kim et al.
Appl. No. : 14/174,754
Filed : February 6, 2014
Page : 3 of 4

Docket No.: 112174-8003.US00

In addition, I hereby confirm the sale, assignment, and transfer to the Assignee of the entire right, title and interest throughout the world in said inventions and improvements that occurred by operation of an employment agreement between me and the Assignee existing at the time said inventions and improvements were made. Should I have any remaining interest, I hereby sell, assign, and transfer any right, title and interest I may have in said inventions and improvements anywhere in the world to the Assignee.

The foregoing assignments, sale and transfer have been made for good and valuable consideration in accordance with the aforementioned employment agreement.

I hereby represent and covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with the assignment of said inventions and improvements to the Assignee.

I further covenant for myself and my respective heirs, legal representatives and assigns, to assist the Assignee in handling various procedures, tasks and documentation in connection with this assignment, including, but not limited to, providing to the Assignee promptly upon the request of the Assignee all pertinent facts and documents relating to said invention and improvements, and said patents, said legal equivalents or other legal instrument as may be known and accessible to me and testifying as to the same in any interference, litigation, or proceeding relating thereto, and promptly executing and delivering to the Assignee or its legal representative any and all papers, documents, instruments or affidavits in connection with obtaining, maintaining, issuing or enforcing said application, said inventions and improvements, and said patents, said equivalents and other legal instrument which may be necessary or desirable to carry out the purposes thereof.

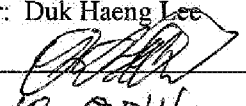
I hereby authorize and request the Commissioner of Patents and Trademarks to issue one or more patents in the United States for said inventions and improvements to Hojin Platech Co., Ltd. as assignee of the entire interest, for the sole use and benefit of Assignee, its successors and assigns.

I am competent to execute the above declaration and assignment. I hereby have duly executed the declaration and assignment below with my name.

Inventor : Kim et al.
Appl. No. : 14/174,754
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Docket No.: 112174-8003.US00

Full name of inventor: Duk Haeng Lee

Inventor's signature: 

Date: March 10, 2014

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PATENT
REEL: 032440 FRAME: 0199

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Pan Soo Kim et al.

Application No.: 14/174,754

Confirmation No.: 1088

Filed: February 6, 2014

For: COPPER PLATING SOLUTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

DECLARATION AND ASSIGNMENT BY THE INVENTOR
UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012

I, Woon Suk Jung, hereby declare that:

I believe I am an original joint inventor of a claimed invention in a patent application
entitled:

COPPER PLATING SOLUTION

the specification of which was filed at the U.S. Patent and Trademark Office on February 6, 2014,
as Application Serial No. 14/174,754, and identified as Attorney Docket No. 112174-8003.US00.

I believe the following persons are additional original joint inventors of the above-
identified patent application:

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Duk Haeng Lee of Bucheon-Si, Republic of Korea.

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I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

I hereby assign to Hojin Platech Co., Ltd., a corporation of Republic of Korea, having a place of business at 15 Block 1 Lot, Banwol Industrial Complex, Monknae-ro 119-91, Danwon-Gu, Ansan-Si, Gyeonggi-do, 425-100, Republic of Korea, and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in an application for United States Patent filed by me, entitled *COPPER PLATING SOLUTION*, filed on February 6, 2014, and assigned U.S. Application Number 14/174,754.

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Inventor : Kim et al.
Appl. No. : 14/174,754
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Page : 3 of 4

Docket No.:112174-8003.US00

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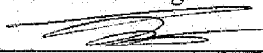
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Full name of inventor: Woon Suk Jung

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Date: March 10, 2014

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RECORDED: 03/14/2014

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